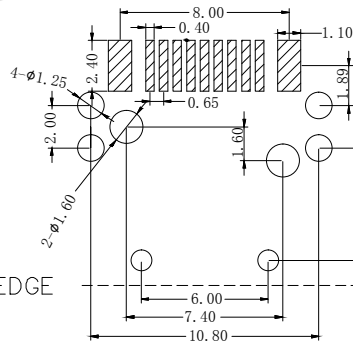
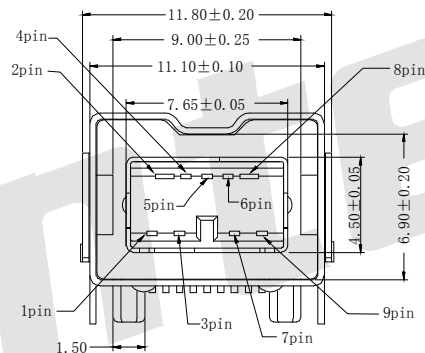
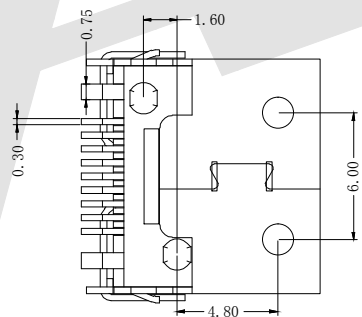
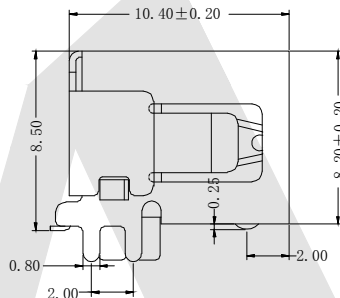
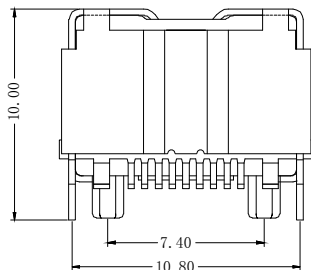
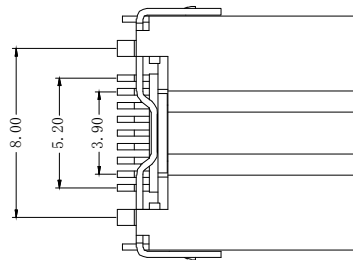


HSF



ROHS



PCB LAYOUT

Specifications:

Current Rating: 1.0A Max
Contact Resistance: 50 milliohms MAX
Dielectric Withstanding Voltage: 300V AC AT Sea Level
Insulation Resistance: 100 Megohms MIN
Operating Temperature: -20° C to +85° C

Housing:

Temperature Thermoplastics, PBT UL 94V-0

Contact:

Copper Alloy T=0.25mm Plated Gold in Mating Area;
Tin On Solder Tails

Shell:

Copper Alloy/Steel T=0.30mm Nickel/Plating

Ordering Code:

IEFM03 - X - X - X - X - X
① ② ③ ④ ⑤ ⑥

① Series No:

② Shell Material:

B: Brass I: Iron
S: stainless steel

③ Insulator Material:

P: PBT+30%GF
L: LCP
T: PA6T

④ Contact Material:

B: Brass
P: phosphor copper

⑤ Contact Plating

G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold

⑥ Packing

A: Tray
B: Bag
C: Tube
D: Tape Reel

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE:
As Shown

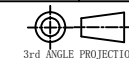
UNIT:
mm

DRAW
Lv Xun Hua

DATE
29/06/2019

CHECK
BobYang

DATE
29/06/2019



ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: 1394 9P Receptacle SMT
(Oblique foot point)

DRAWING NO: IEFM03-XXXXXX

PRODUCT NO: IEFM03-XXXXXX

D

D

REV

DESCRIPTION

DATE

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